

Layer Stack Up Detail for: LM3410XMFLLEDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
 LM3410XMFLLEDEV Evaluation Board

DESIGNED FOR:
 Public Release

FILE NAME:
 LM3410XMFLLEDEV.PcbDoc

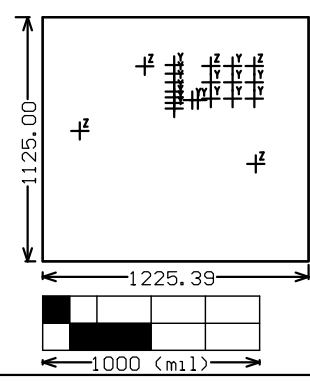
MODIFIED BY:
 Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
 10.0.0.27009

SIZE	QTY	SYM	PLTD
0.015	16	Y	PLTD
0.055	5	Z	PLTD



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SU600051

REV: A

LAYER NAME = M2006cub19m1a0ns

PLOT NAME = LM3410XMFLLEDEV.GM11

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFLLEDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
LM3410XMFLLEDEV Evaluation Board

DESIGNED FOR:
Public Release

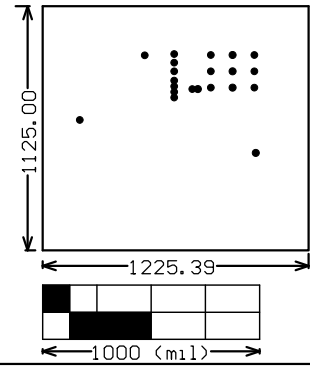
FILE NAME:
LM3410XMFLLEDEV.PcbDoc

MODIFIED BY:
Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = M2006cbln01a.ms

PLOT NAME = LM3410XMFLLEDEV.GM11

BOARD #: SU600051

REV: A

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFL EDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
 LM3410XMFL EDEV Evaluation Board

DESIGNED FOR:
 Public Release

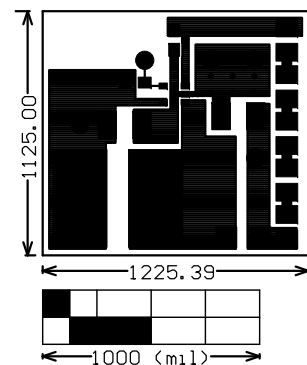
FILE NAME:
 LM3410XMFL EDEV.PcbDoc

MODIFIED BY:
 Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
 10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = M2006cubn001a.ms

PLOT NAME = LM3410XMFL EDEV.GM11

BOARD #: SU600051

REV: A

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFL EDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
 LM3410XMFL EDEV Evaluation Board

DESIGNED FOR:
 Public Release

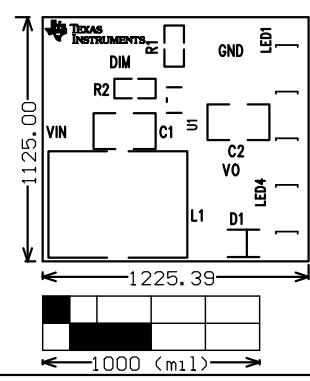
FILE NAME:
 LM3410XMFL EDEV.PcbDoc

MODIFIED BY:
 Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
 10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = M2006cub100110ns

PLOT NAME = LM3410XMFL EDEV.GM11

BOARD #: SU600051

REV: A

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFLLEDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
 LM3410XMFLLEDEV Evaluation Board

DESIGNED FOR:
 Public Release

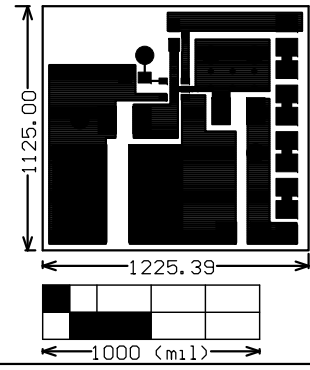
FILE NAME:
 LM3410XMFLLEDEV.PcbDoc

MODIFIED BY:
 Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
 10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = M2006cub1001a.ms

PLOT NAME = LM3410XMFLLEDEV.GM11

BOARD #: SU600051

REV: A

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFLDEUV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
 LM3410XMFLDEUV Evaluation Board

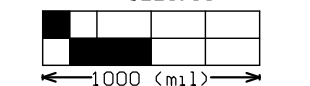
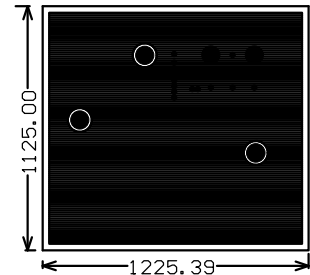
DESIGNED FOR:
 Public Release

FILE NAME:
 LM3410XMFLDEUV.PcbDoc

MODIFIED BY:
 Kryton Solutions

SCALE: 1.00

LAYOUT BY:
 ALTUM DESIGNER VERSION:
 10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600051	REV: A	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
LAYER NAME = M2006	GENERATED : 7/23/2013 4:39:27 PM	TEXAS INSTRUMENTS	
PLOT NAME = LM3410XMFLDEUV.GM11			

Layer Stack Up Detail for: LM3410XMFL EDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
LM3410XMFL EDEV Evaluation Board

DESIGNED FOR:
Public Release

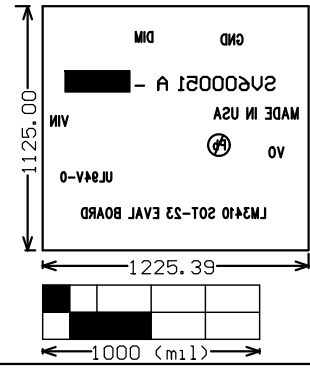
FILE NAME:
LM3410XMFL EDEV.PcbDoc

MODIFIED BY:
Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = M2006-0001

PLOT NAME = LM3410XMFL EDEV.GM11

BOARD #: SU600051

REV: A

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM3410XMFLLEDEV.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 1225Mil X 1125Mil

Number of Layers : 2
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 32 MIL
 MIN. VIA PAD SIZE: 85 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)

INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR:

GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)

IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1

N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURER'S ID/LOGO: RAIL METAL SILK



PROJECT TITLE:
LM3410XMFLLEDEV Evaluation Board

DESIGNED FOR:
Public Release

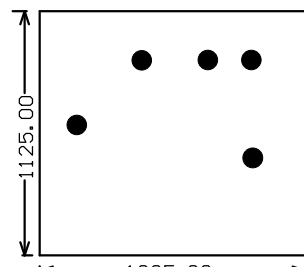
FILE NAME:
LM3410XMFLLEDEV.PcbDoc

MODIFIED BY:
Kryton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SU600051

REV: A

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

LAYER NAME = M2006cbln001a.ms

PLOT NAME = LM3410XMFLLEDEV.GM11

GENERATED : 7/23/2013 4:39:27 PM

TEXAS INSTRUMENTS